

zinc, nickel, iron, niobium, molybdenum, titanium, nickel/chromium alloy, iron/nickel/chromium alloy and aluminum, a dielectric material deposited on the first metal layer and having a thickness of from about 0.03 to about 2 microns and wherein the dielectric material contains a cation other than that of the metal from which the metal foil is formed, and a second metal layer, said first and second metal layers each having an exposed surface.

Add Claims 36-46 which reads as follows:

--36. The layered structure according to Claim 35 wherein said second metal layer is patterned.

37.. A layered structure for forming a thin layer capacitor comprising:

a flexible polymer support sheet,

an un-patterned first metal layer formed on said flexible polymer support sheet, said first metal layer being release-able from said support sheet, the metal being selected from the group consisting of copper, zinc, nickel, iron, niobium, molybdenum, titanium, nickel/chromium alloy, iron/nickel/chromium alloy and aluminum,

a dielectric layer formed on said un-patterned first metal layer between about 0.03 and about 2 microns thick, and

a second metal layer formed on said flexible polymer support sheet, the metal being selected from the group consisting of copper, zinc, nickel, iron, niobium, molybdenum, titanium, nickel/chromium alloy, iron/nickel/chromium alloy and aluminum, said second metal layer having an exposed surface.

38. The layered structure according to Claim 37 wherein said support sheet is polymeric material.

39. The layered structure according to Claim 37 wherein said second metal layer is patterned..

40. A layered structure for acting as or forming at least one thin layer capacitor comprising in sequence a first metal layer selected from the group consisting of copper, zinc, nickel, iron, niobium, molybdenum, titanium, nickel/chromium alloy, iron/nickel/chromium alloy and aluminum, a dielectric material deposited on the first metal layer and having a thickness of from about 0.03 to about 2, a second metal layer, and a barrier lalyer between about 0.01 and about 0.08 microns thick between said first metal layer and said dielectric material layer.

41. The layered structure according to Claim 40 wherein said barrier layer is formed of material selected from the group consisting of tungsten oxide, strontium oxide, and mixed tungsten/strontium oxides.
42. The layered structure according to Claim 40 wherein said barrier layer is formed of material selected from the group consisting of  $\text{BAWO}_4$ , silica, alumina, nickel and platinum.
43. The layered structure according to Claim 40 wherein said barrier layer is formed of material selected from the group consisting of ceria and  $\text{Sr}_{1-x}\text{Ba}_x\text{WO}_4$ .
44. A layered structure for acting as or forming at least one thin layer capacitor comprising in sequence a first metal layer selected from the group consisting of copper, zinc, nickel, iron, niobium, molybdenum, titanium, nickel/chromium alloy, iron/nickel/chromium alloy and aluminum, a dielectric material deposited on the first metal layer and having a thickness of from about 0.03 to about 2 microns, a second metal layer, and an adhesion layer between about 0.0001 and about 0.05 microns thick between said dielectric material layer and said second metal layer.
45. The layered structure according to Claim 44 wherein said adhesion layer is a functionally gradient material..
46. A layered structure for acting as or forming at least one thin layer capacitor comprising in sequence a first metal layer selected from the group consisting of copper, zinc, nickel, iron, niobium, molybdenum, titanium, nickel/chromium alloy, iron/nickel/chromium alloy and aluminum, a dielectric material deposited on the first metal layer and having a thickness of from about 0.03 to about 2 microns, and a second metal layer, said dielectric material layer being chemically doped to be lossy having an electrical conductivity value of from about  $10^{-1}$  to about  $10^{-5}$  amperes per  $\text{cm}^2$ .

REMARKS

Claims 2-3, 5-35 are pending in the present application. Claims 8, 9, and 24-28 are deleted with this amendment; Claims 36-46 are added with entry of this Amendment.

Claims 40, 44, and 46 correspo